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(71)Applicant : NIPPON DENKAI KK
HITACHI CHEM CO LTD

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(72)Inventor : KAWASAKI TOSHIO
YAMADA MASAHIKO
KUMAKURA YOSHITOSHI
KOBAYASHI KAZUHIITO

(54) COPPER FOIL FOR PRINTED WIRING BOARD AND ITS PRODUCING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a copper foil for printed wiring board, and its producing method, exhibiting excellent stripping strength without increasing the surface roughness in order to deal with fine patterning of circuit wiring and high function of a basic material.

SOLUTION: The copper foil for printed wiring board comprises a rust prevention processing layer, a coupling agent processing layer, and an adhesive property imparting layer of epoxy resin polymer having weight average molecular weight of 70,000 or above wherein the adhesive property imparting layer has a thickness of 0.5-5 g/m² expressed in terms of weight. When an epoxy silane based coupling agent is employed, a copper foil for printed wiring board exhibiting excellent stripping strength is obtained. In the process for producing a copper foil for printed wiring board by forming an adhesive property imparting layer on a copper foil, the copper foil is coated with a solution containing epoxy resin polymer by 1-10%.

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